

GS1MH-E

SURFACE MOUNT GLASS PASSIVATED RECTIFIER

VOLTAGE: 1000V

CURRENT: 1.0A



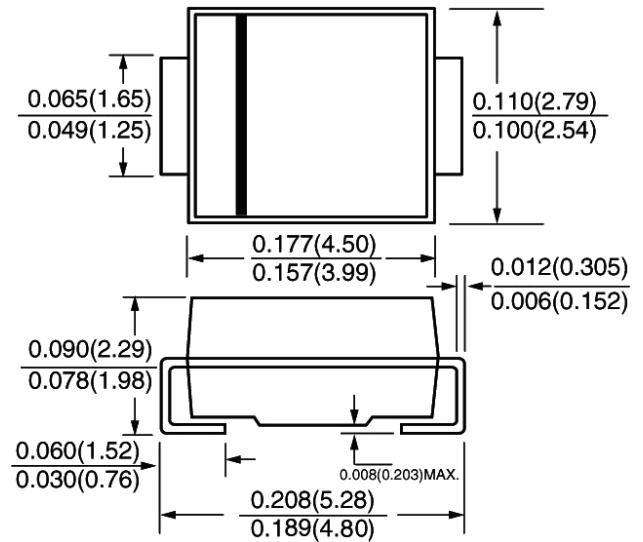
FEATURE

Ideal for surface mount pick and place application
Low profile package
Built-in strain relief
High surge capability
High temperature soldering guaranteed
260°C/10sec/at terminals
Halogen Free

MECHANICAL DATA

Terminal: Solder plated, solderable per MIL-STD 750, method 2026
Case: Molded with UL-94 class V-0 recognized Halogen Free Epoxy
Polarity: color band denotes cathode

SMA / DO-214AC



Dimensions in inches and (millimeters)

MAXIMUM RATINGS AND ELECTRICAL CHARACTERISTICS

(single-phase, half-wave, 60HZ, resistive or inductive load rating at 25°C, unless otherwise stated,)

	Symbol	GS1MH-E	units
Maximum Recurrent Peak Reverse Voltage	V _{rrm}	1000	V
Maximum RMS Voltage	V _{rms}	700	V
Maximum DC blocking Voltage	V _{dc}	1000	V
Maximum Average Forward Rectified Current 3/8"lead length	I _{f(av)}	1.0	A
Peak Forward Surge Current 8.3ms single half sine-wave superimposed on rated load	I _{fsm}	30.0	A
Maximum Instantaneous Forward Voltage at rated Forward current	V _f	1.1	V
Maximum DC Reverse Current at rated DC blocking voltage	I _r	5.0 200.0	μA
Reverse Recovery Time (Note 1)	T _{rr}	1000~2000	nS
Typical Junction Capacitance (Note 2)	C _j	15.0	pF
Typical Thermal Resistance (Note 3)	R _{th(jl)}	30.0	°C/W
Typical Thermal Resistance (Note 4)	R _{th(ja)}	75.0	°C/W
Storage and Operating Junction Temperature	T _j , T _{stg}	-50 to +150	°C

- Note:
- Reverse Recovery Condition I_f = 0.5A, I_r = 1.0A, I_{rr} = 0.25A, in the test and applications can allowed tolerance range 5%
 - Measured at 1.0 MHz and applied voltage of 4.0Vdc
 - Thermal Resistance from Junction to terminal mounted on 5×5mm copper pad area
 - Thermal Resistance from Junction to ambient

RATINGS AND CHARACTERISTIC CURVES GS1MH-E

Fig. 1 – Forward Current Derating Curve

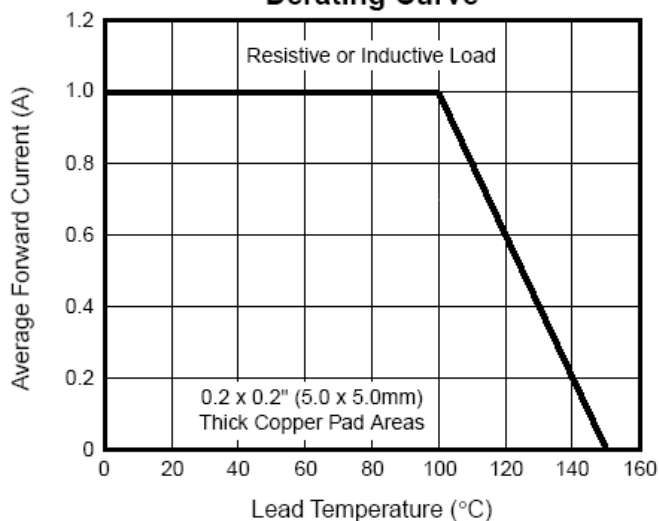


Fig. 2 – Maximum Non-Repetitive Peak Forward Surge Current

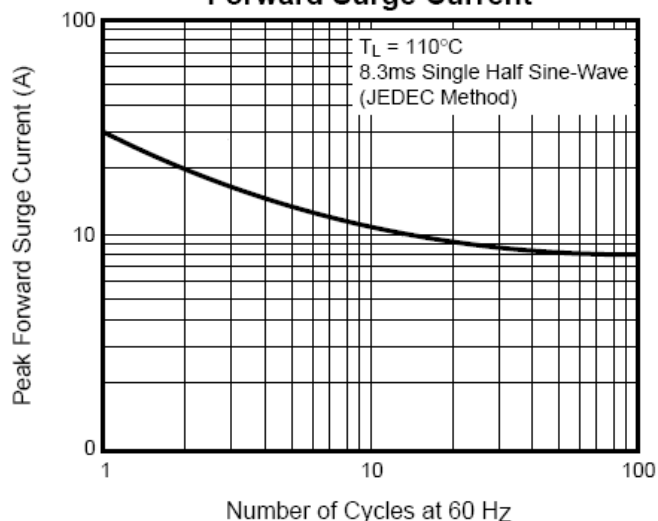


Fig. 3 – Typical Instantaneous Forward Characteristics

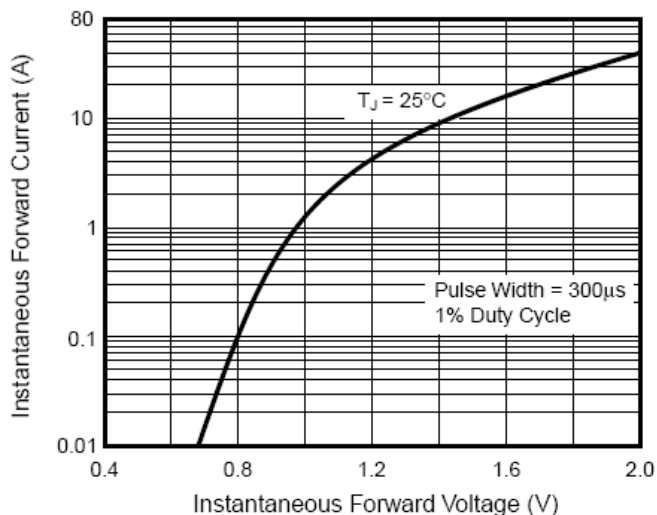


Fig. 4 – Typical Reverse Leakage Characteristics

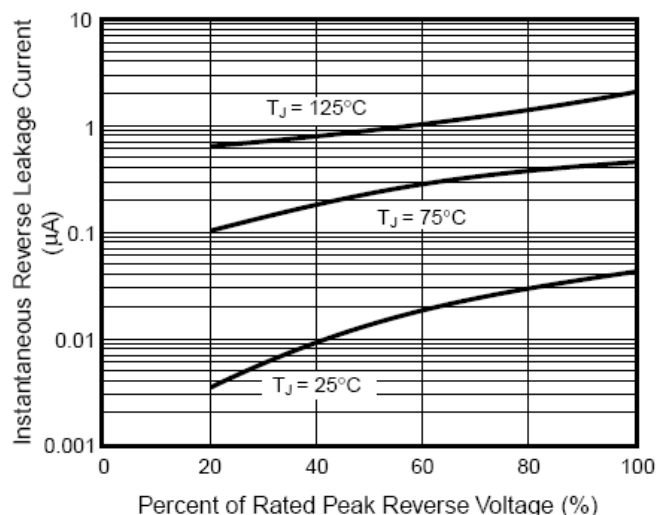


Fig. 5 – Typical Junction Capacitance

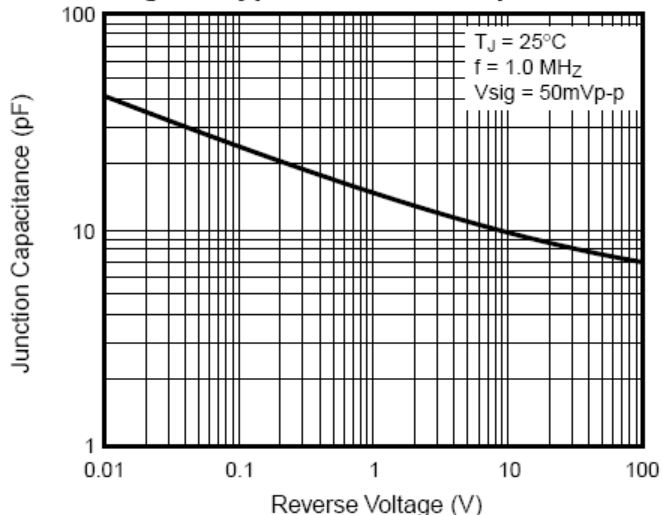


Fig. 6 – Transient Thermal Impedance

